

THERMAL INTERFACE MATERIAL
AND SOLDER PREFORMS

Abstract of the Disclosure:

5 A solder preform having multiple layers including a
solder layer filled with additives interposed between two
unfilled layers for improved wettability. A solder preform
having a sphere which contains a solder material filled with
additives, and an unfilled surface layer for improved
wettability. A thermal interface material having a bonding
10 component and an additive component which is a CTE modifying
component and/or a thermal conductivity enhancement component.
Active solders containing intrinsic oxygen getters.